

Chemical content 74HCT4538D-Q100



Type number	Package	Package description	Total product weight
74HCT4538D-Q100	SOT109-1	SO16	163.30162 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935298861118	6	1	260	30 s	1	235	20 s	3	Nijmegen, Netherlands; Suzhou, China; Bangkok, Thailand	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.01557	77.86000	0.00954
		Polymer	Acrylic resin	Proprietary	0.00304	15.18000
		Resin system	Proprietary	0.00139	6.96000	0.00085
		subTotal		0.02000	100.00000	0.01225
Die	Doped silicon	Silicon (Si)	7440-21-3	1.45984	100.00000	0.89395
		subTotal		1.45984	100.00000	0.89395
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	54.63012	97.47000	33.45351
		Iron (Fe)	7439-89-6	1.34516	2.40000	0.82372
		Phosphorus (P)	7723-14-0	0.01681	0.03000	0.01030
		Zinc (Zn)	7440-66-6	0.05605	0.10000	0.03432
		subTotal		56.04814	100.00000	34.32185
Mould Compound	Additive	Non hazardous	Proprietary	4.89961	4.70000	3.00034
	Filler	Silica fused	60676-86-0	82.35513	79.00000	50.43130
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	6.25482	6.00000	3.83023
	Pigment	Carbon black	1333-86-4	0.20849	0.20000	0.12767
	Polymer	1.4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	4.16988	4.00000	2.55348
		Non hazardous	Proprietary	4.27413	4.10000	2.61732
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	2.08494	2.00000	1.27674
	subTotal		104.24700	100.00000	63.83708	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.04268	3.00000	0.02614
		Nickel (Ni)	7440-02-0	1.31321	92.30000	0.80416
		Palladium (Pd)	7440-05-3	0.04411	3.10000	0.02701
		Silver (Ag)	7440-22-4	0.02276	1.60000	0.01394
		subTotal		1.42276	100.00000	0.87125
Wire	Pure metal	Copper (Cu)	7440-50-8	0.10388	100.00000	0.06361
		subTotal		0.10388	100.00000	0.06361

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